Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
[List multiple models if applicable.]
HP EliteDesk 800 G4 TWR Business PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td></td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>Acbel 250W EPA92 HV C4</td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>O/P CABLE</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
Components, parts and materials containing refractory ceramic fibers

Components, parts and materials containing radioactive substances

**2.0 Tools Required**

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screwdriver</td>
<td>T-15</td>
</tr>
<tr>
<td>Micro shear</td>
<td>170II</td>
</tr>
<tr>
<td>Screwdriver</td>
<td>PH1</td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

**3.0 Product Disassembly Process**

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Press access panel latch and remove access panel.(see Figure 1 below)
2. Remove the cable from the driver cage hook.(see Figure 2 below)
3. Remove front bezel from chassis.(see Figure 3 below)
4. Rotate up driver cage.(see Figure 4 below)
5. Remove HDD SATA/power cable.(see Figure 5-6 below)
6. Remove HDD from HDD cage.(see Figure 7 below)
7. Disconnect HDD SATA cable from MB.(see Figure 8 below)
8. Remove ODD SATA/power cable from ODD and MB.(see Figure 9-12 below)
9. Remove ODD from chassis.(see Figure 13-14 below)
10. Remove memory from MB.(see Figure 15 below)
11. Remove PSU/Speaker/system fan cables from MB.(see Figure 16-20 below)
12. Remove system fan from chassis.(see Figure 21 below)
13. Remove heatsink from MB.(see Figure 22-23 below)
14. Separate the fan from CPU heatsink .(see Figure 24-25 below)
15. Remove the CPU from the MB(see Figure 26-27 below)
16. Remove the battery from the MB.(see Figure 28 below)
17. Remove MB from chassis.(see Figure 29-30 below)
18. Remove Speaker from chassis.(see Figure 31 below)
19. Remove PSU cover.(see Figure 32-38 below)
20. Disconnect all the cables and remove the Electrolytic Capacitors.(see Figure 49-43 below)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Figure 1 Press access panel latch remove access panel

Figure 2 Remove the cable from the hook

Figure 3 Remove front bezel from chassis

Figure 4 Rotate up driver cage

Figure 5 Disconnect SATA cable from HDD

Figure 6 Disconnect SATA power cable from HDD
Figure 7 Remove HDD from driver cage
Figure 8 Disconnect HDD SATA cable from MB

Figure 9 Disconnect SATA cable from ODD
Figure 10 Disconnect SATA power cable from ODD

Figure 11 Disconnect ODD SATA cable from MB
Figure 12 Disconnect SATA power cable from MB

PSG instructions for this template are available at EL-MF877-01
<table>
<thead>
<tr>
<th>Figure 13 Press ODD latch in ODD cage</th>
<th>Figure 14 Remove ODD from ODD cage</th>
</tr>
</thead>
<tbody>
<tr>
<td>[Image]</td>
<td>[Image]</td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>Figure 15 Remove memory from MB</th>
<th>Figure 16 Disconnect PSU P1 cable from MB</th>
</tr>
</thead>
<tbody>
<tr>
<td>[Image]</td>
<td>[Image]</td>
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</tbody>
</table>

<table>
<thead>
<tr>
<th>Figure 17 Disconnect PSU P2 cable from MB</th>
<th>Figure 18 Disconnect PSU P3 cable from MB</th>
</tr>
</thead>
<tbody>
<tr>
<td>[Image]</td>
<td>[Image]</td>
</tr>
</tbody>
</table>
Figure 19 Disconnect Speaker cable from MB

Figure 20 Disconnect system fan cable from MB

Figure 21 Use PH1 screwdriver to remove system fan from chassis

Figure 22 Disconnect heatsink fan cable from MB

Figure 23 Use T-15 screwdriver to loose the screws and remove heatsink

Figure 24 Use PH1 screwdriver to loose the screws and remove the fan
Figure 25 Separate the fan from heatsink

Figure 26 Rotate the handle and open it up

Figure 27 Remove CPU from MB

Figure 28 Remove battery from MB

Figure 29 Use T-15 screwdriver to loose the screws of MB from board

Figure 30 Remove MB from chassis
Figure 31 Use T-15 screwdriver loose the screws of speaker and remove it

Figure 32 Use T-15 screwdriver remove the screws on the PSU chassis

Figure 33 Press the PSU’s latch on chassis

Figure 34 Remove the Power supply from chassis

Figure 35 Use Micro shear 170II to cut the cable tie

Figure 36 Use PH1 screwdriver to remove screw for bottom

PSG instructions for this template are available at EL-MF877-01
Figure 37 Use PH1 screwdriver to remove screw for top

Figure 38 Remove cover

Figure 39 Use PH1 screwdriver to remove FG screw

Figure 40 Disconnect fan connector and inlet connector

Figure 41 Use PH1 screwdriver to remove PCB1 screw

Figure 42 Use PH1 screwdriver to remove AC inlet & Fan screw
Figure 43 52 Heat the solder of Electrolytic Capacitors greater than 2.5cm in diameter or height and remove it